

ABSTRACT

A method for encapsulating an integrated circuit chip is described. An integrated circuit chip is attached to a substrate. A dam is formed surrounding the integrated circuit chip. At least one corner of the integrated circuit chip is covered with a stress buffering material. The integrated circuit chip and all of the substrate within the dam are coated with an encapsulation material wherein the encapsulation material covers the stress buffering material and wherein the stress buffering material prevents delamination of the encapsulation material at the corners of the integrated circuit chip.